

### **Amendments to the Claims**

#### **Claims 1-35 (Canceled)**

Claim 36 **(New)** An apparatus for plating a surface of a substrate to fill a wiring recess in the surface with a metal, said apparatus comprising:

- a frame;
- a load/unload unit on which the substrate is held;
- a transfer mechanism disposed in said frame; and
- a plurality of processing units disposed in said frame so as to surround said transfer mechanism.

Claim 37 **(New)** An apparatus according to claim 36, wherein said transfer mechanism is linearly movable.

Claim 38 **(New)** An apparatus according to claim 36, wherein said processing units include an electrolytic plating unit for performing an electrolytic plating process.

Claim 39 **(New)** An apparatus according to claim 38, wherein said processing units include a cleaning and drying device for cleaning and spin drying the substrate after the electrolytic plating process.

Claim 40 **(New)** An apparatus according to claim 36, wherein said processing units include an electroless plating unit for performing an electroless plating process.

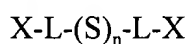
Claim 41 **(New)** An apparatus according to claim 40, wherein said processing units include a pretreatment unit for performing a pre-treatment process of the electroless plating process.

Claim 42 **(New)** An apparatus according to claim 40, wherein said electroless plating unit comprises an electroless plating bath having a plating liquid comprising copper sulfate ( $\text{CuSO}_4 \cdot 5\text{H}_2\text{O}$ ) having a concentration of 100 to 250 g/l.

Claim 43 **(New)** An apparatus according to claim 40, wherein said electroless plating unit comprises an electroless plating bath having a plating liquid comprising sulfuric acid ( $\text{H}_2\text{SO}_4$ ) having a concentration of 10 to 100 g/l.

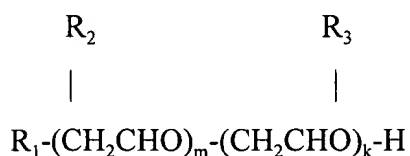
Claim 44 **(New)** An apparatus according to claim 40, wherein said electroless plating unit comprises an electroless plating bath having a plating liquid comprising chlorine ions having a concentration of 0 to 100 mg/l.

Claim 45 **(New)** An apparatus according to claim 40, wherein said electroless plating unit comprises an electroless plating bath having a plating liquid comprising at least 0.14 to 70  $\mu\text{mol/l}$  of a sulfur compound expressed by a formula



where L is an alkyl group having a carbon number of 1 to 6 which is substituted by a lower alkyl group, a lower alkoxy group, a hydroxyl group, or a halogen atom; n is an integer; and X is a hydrogen atom, a  $-\text{SO}_3\text{M}$  group, or a  $-\text{PO}_3\text{M}$  group; and M indicates a hydrogen atom, an alkali metal atom, or an amino group.

Claim 46 **(New)** An apparatus according to claim 40, wherein said electroless plating unit comprises an electroless plating bath having a plating liquid comprising at least 10 to 5000 mg/l of a macromolecular compound expressed in a formula



where  $\text{R}_1$  indicates a residue of a higher alcohol group having a carbon number of 8 to 25, a residue of an alkyl phenol with an alkyl group having a carbon number of 1 to 25, a residue of an

alkyl naphthol with an alkyl group having a carbon number of 1 to 25, a residue of a fatty acid amide having a carbon number of 3 to 22, a residue of an alkylamine having a carbon number of 2 to 4, or a hydroxyl group;  $R_2$  and  $R_3$  indicate a hydrogen atom or a methyl group; and m and k indicate an integer from 1 to 100.

Claim 47 (New) An apparatus according to claim 40, wherein said electroless plating unit comprises an electroless plating bath having a plating liquid comprising at least 0.01 to 100 mg/l of a nitrogen compound.

Claim 48 (New) An apparatus according to claim 36, wherein said frame is rectangular in shape.